

SOD323 SILICON HIGH CURRENT SCHOTTKY BARRIER DIODE "SuperBAT"

FEATURES

- Low V_F
- High current capability
- Miniature surface mount package

APPLICATIONS

- DC - DC converters
- Mobile telecomms
- PCMCIA

DEVICE MARKING

- Partmark detail - BD

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Continuous Reverse Voltage	V_R	40	V
Forward Current (Continuous)	I_F	400	mA
Forward Voltage @ $I_F = 400\text{mA}$	V_F	500	mV
Average Peak Forward Current; D.C. = 50%	I_{FAV}	1000	mA
Non Repetitive Forward Current	I_{FSM}	6.75 3	A A
	$t \leq 100\mu\text{s}$ $t \leq 10\text{ms}$		
Power Dissipation at $T_{amb} = 25^\circ\text{C}$	P_{tot}	250	mW
Storage Temperature Range	T_{stg}	-55 to +150	$^\circ\text{C}$



PINOUT - TOP VIEW

Cathode



Anode

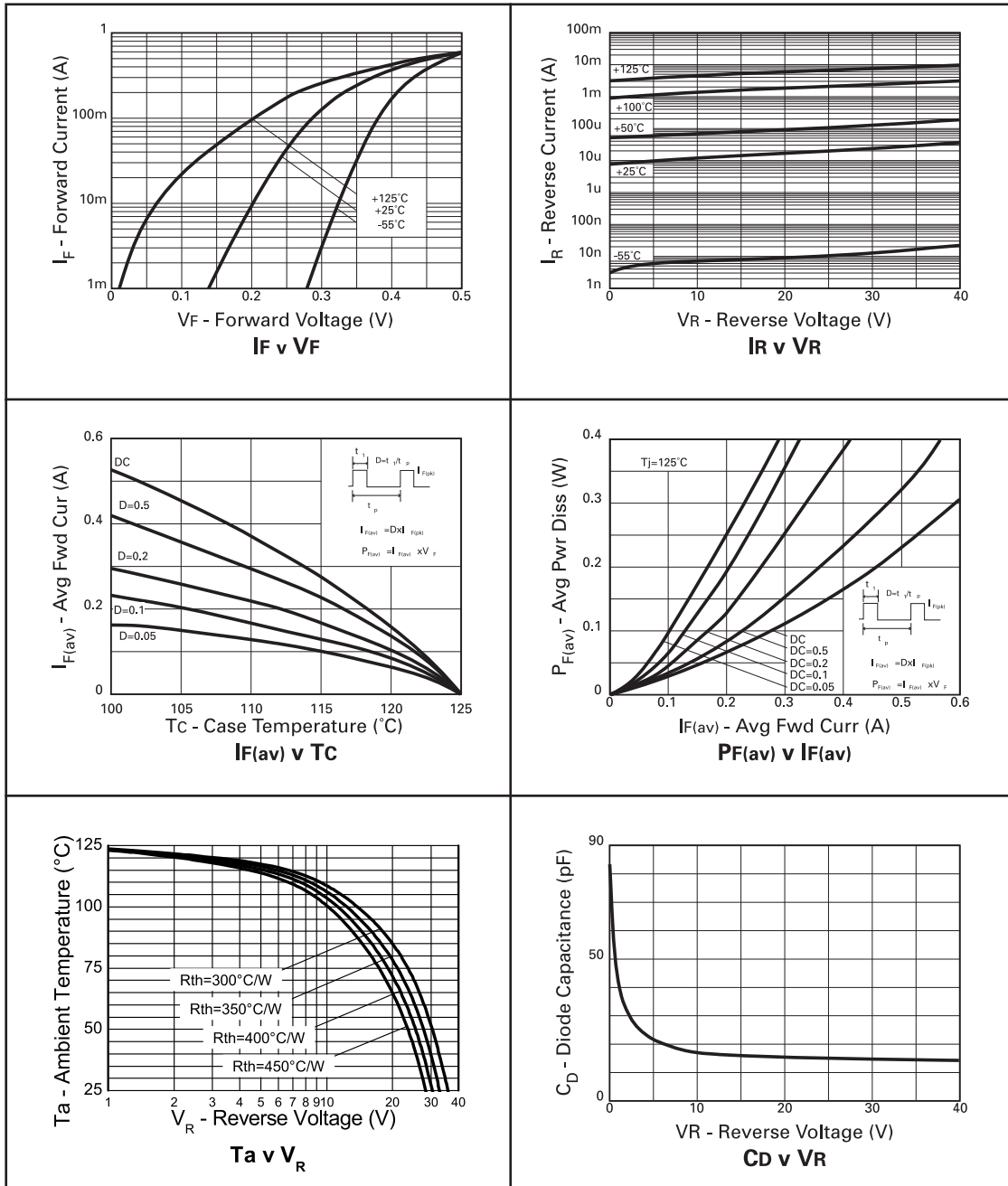
Partmark is for example only

ELECTRICAL CHARACTERISTICS (at $T_{amb} = 25^\circ\text{C}$ unless otherwise stated)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Reverse Breakdown Voltage	$V_{(BR)R}$	40	60		V	$I_R = 200\mu\text{A}$
Forward Voltage	V_F		270 300 370 425 550 640 810 440	300 350 460 500 670 780 1050	mV mV mV mV mV mV mV mV	$I_F = 50\text{mA}$ $I_F = 100\text{mA}$ $I_F = 250\text{mA}$ $I_F = 400\text{mA}$ $I_F = 750\text{mA}$ $I_F = 1000\text{mA}$ $I_F = 1500\text{mA}$ $I_F = 500\text{mA}, T_{amb} = 100^\circ\text{C}$
Reverse Current	I_R		15	40	μA	$V_R = 30\text{V}$
Diode Capacitance	C_D		20		pF	$f = 1\text{MHz}, V_R = 25\text{V}$

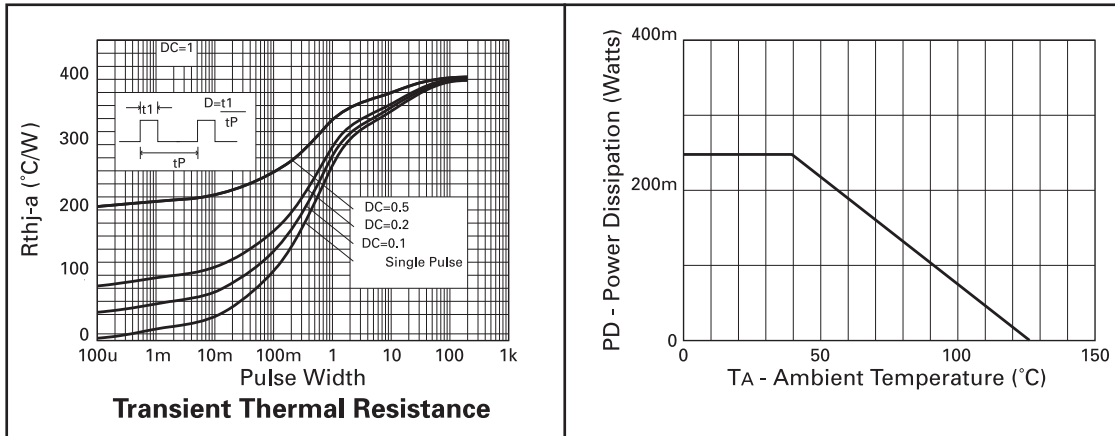
ZHCS400

TYPICAL CHARACTERISTICS



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TYPICAL CHARACTERISTICS (Cont.)



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NOTES:

Definitions

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Product status key:

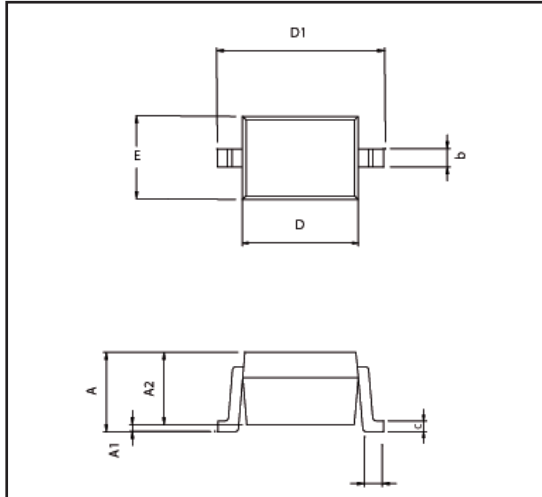
- "Preview"Future device intended for production at some point. Samples may be available
- "Active"Product status recommended for new designs
- "Last time buy (LTB)"Device will be discontinued and last time buy period and delivery is in effect
- "Not recommended for new designs"Device is still in production to support existing designs and production
- "Obsolete"Production has been discontinued

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PACKAGE OUTLINE



PACKAGE DIMENSIONS

DIM	Millimeters		DIM	Millimeters	
	Min	Max		Min	Max
A	-	1.150	D	1.520	1.800
A1	0.000	0.100	D1	2.300	2.700
A2	0.800	-	E	1.150	1.450
b	0.250	0.400	L	0.100	0.400
c	0.080	0.200	-	-	-

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Issue 5 - February 2008